

**REMARKS**

**Summary of the Office Action**

Claims 10-11, 15, 19, 21, and 23 stand objected to because of informalities.

Claims 1-22 and 24-27 stand rejected under 35 U.S.C. § 102(b) as being anticipated by USPN 5,790,222 to Kim (*Kim222*).

Claim 23 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over *Kim222* in view of USPN 6,100,953 to Kim et al. (*Kim953*).

**Summary of the Response**

Applicant has amended claims 10-11, 15, 19, 21 and 23, and have added new claims 28-29 to further define the invention. Accordingly, Claims 1-29 are presently pending.

**The Objections to the Claims**

Claims 10-11, 15, 19, 21, and 23 stand objected to because of informalities. Applicant has amended claims 10-11, 15, 19, 21, and 23 in accordance with the comments of the Examiner. Accordingly, Applicant respectfully requests that the objections to the claims be withdrawn.

**The Rejections under 35 U.S.C. §§ 102(b) and 103(a)**

Claims 1-22 and 24-27 stand rejected under 35 U.S.C. § 102(b) as being anticipated by USPN 5,790,222 to Kim (*Kim222*). Claim 23 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over *Kim222* in view of USPN 6,100,953 to Kim et al. (*Kim953*). Applicant respectfully traverses the rejections for at least the following reasons.

With respect to independent claim 1, Applicant respectfully asserts that the applied art, whether taken singly or combined, does not teach or suggest a combination including an active

layer disposed below a second data line, a source electrode and a drain electrode, as claimed.

The Office Action asserts that undoped amorphous silicon layer 45 of *Kim222* is an “active layer” as claimed, that lower data bus line 49 of *Kim222* is a “second data line” as claimed, and that source electrode 47 of *Kim222* is a “source electrode” as claimed. Applicants respectfully disagree. Applicant respectfully assert that, while the silicon layer 45 of *Kim222* is disposed under the source electrode 47, the silicon layer 45 is not disposed under the lower data bus line 49.

With respect to independent claim 15, Applicant respectfully assert that the applied art, whether taken singly or combined, do not teach or suggest a method including steps of sequentially depositing a semiconductor layer and a conductive layer on an entire surface of a insulating substrate including a gate line and a first data line and forming a second data line by patterning the semiconductor layer and the conductive layer, as claimed. Applicants respectfully assert that the rejection of claim 15 is improper at least because the rejection does not relate the applied art to the claimed method steps but rather to the device structure of claim 1. Moreover, in *Kim222*, lower data bus line 49 (which is alleged to be a “second data line”) does not have a semiconductor material thereunder as would result from the claimed method steps. That is, the semiconductor and the conductive layers are sequentially deposited on an entire surface and then patterned. Thus, any remaining conductive material would have semiconductive material thereunder. With respect to the amendments made to independent claim 15, Applicant respectfully asserts that the amendments do not relate to any of the foregoing features. Thus,

Applicant respectfully submits that the amendments merely relate to informalities and not to any issues of patentability.

With respect to dependent claims 9-10 and 20-21, Applicant respectfully asserts that the applied art, whether taken singly or combined, do not teach or suggest a C-shaped groove as claimed. Applicants respectfully assert that the exemplary embodiment of Figure 4 clearly illustrates a C-shaped groove. If the Office persists in asserting that *Kim222* teaches a C-shaped groove, Applicant respectfully requests that the alleged C-shaped groove be more clearly pointed out.

Applicant respectfully asserts that the Office Action does not rely on *Kim953* to remedy any of these deficiencies. Further, Applicants respectfully assert that *Kim953* cannot remedy any of the foregoing deficiencies.

Accordingly, Applicants respectfully assert that the rejections under 35 U.S.C. §§ 102(b) and 103(a) are improper and should be withdrawn.

#### **New Claims 28-29**

Applicant has added new claims 28-29 to further define the invention. Applicant respectfully submits that new independent claims 28-29 are allowable.

**Conclusion**

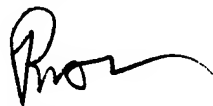
In view of the foregoing, Applicant respectfully requests reconsideration and reexamination of this application, withdrawal of all rejections and objections, and the timely allowance of all pending claims. Should the Examiner feel that there are any issues outstanding after consideration of this response, the Examiner is invited to contact Applicants' undersigned representative to expedite prosecution.

If there are any other fees due in connection with the filing of this response, please charge the fees to our Deposit Account No. 50-0310. If a fee is required for an extension of time under 37 C.F.R. § 1.136 not accounted for above, such an extension is requested and the fee should also be charged to our Deposit Account.

Respectfully submitted,

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